

Please amend the Claims as follows:

1-3. (Cancelled)

4. (Previously Presented) A thin-film capacitor element comprising:
an insulative substrate having a via hole filled with a conductive
material;

a lower electrode;

a dielectric layer; and

an upper electrode;

wherein the lower electrode, the dielectric layer, and the upper
electrode are successively deposited in order on the insulative substrate,

either one of the lower electrode and the upper electrode
connects to an end face of the conductive material in an area not having a
dielectric layer; and

the dielectric layer is shaped like a ring to surround the via hole.

5. (Previously Presented) A thin-film capacitor element according to
Claim 4, wherein an area between the dielectric layer and the via hole is ring
shaped.

6. (Previously Presented) A thin-film capacitor element according to
Claim 4, wherein the insulative substrate is made of low-temperature-sintered
ceramic.